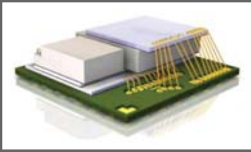
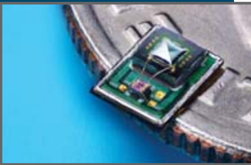
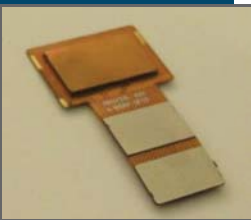
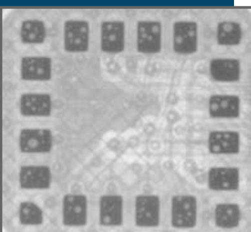
# Advanced Packaging Update:
## *Market and Technology Trends*

*Vol. 2-0617*









This second volume of the Advanced Packaging Update provides an economic outlook for the electronics industry and describes the latest trends in fan-out wafer level packages (FO-WLP) including the new versions mounted on substrates. A special section examines the growing market for sensors in smartphones and industrial applications. TechSearch International's annual survey on substrate design rules is highlighted, with special coverage of suppliers of organic flip chip BGA and CSP substrates worldwide. The design rules include body size, core thickness, via and pad diameter, minimum bump pitch supported, and substrate finish.

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